

Auto Focus (AF) Controller LC898219XI

Overview

This LSI is Closed-Auto Focus control LSI equipped with hall sensor. It consists of 1 system feedback circuit and constant current driver. It has also a built-in EEPROM and temperature sensor.

Features

- Built-in Equalizer Circuit Using Digital Operation
 - AF Control Equalizer Circuit
 - Any Coefficient can be Specified by 2-wire Serial I/F (TWIF)
- 2-wire Serial Interface

(The Communication Protocol is Compatible with I²C)

- Built-in A/D Converter
- Built-in D/A Converter
 - Hall Offset
 - Constant Current Bias
- Built-in Hall Sensor
 - ◆ Si Hall Sensor
- Built-in VGA
 - ◆ Hall Amp
- Built-in EEPROM
 - 128 Byte (16 Byte/Page)
- Built-in OSC
- Built-in Constant Current Driver
 - ♦ 140 mA
- Package
 - ♦ WLCSP 8-pin
- Supply Voltage
 - V_{DD} (2.6 V to 3.3 V)
- This Device is Pb–Free, Halogen Free/BFR Free and is RoHS Compliant



WLCSP8, 0.97x2.25x0.265 CASE 567TE

MARKING DIAGRAM

8219XI YMAZZ

8219XI = Specific Device Code

Y = YearM = Month

A = Assembly Site ZZ = Lot Number

ORDERING INFORMATION

Device	Package	Shipping [†]
LC898219XI-MH	WLCSP8	4000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

PIN DESCRIPTION

Table 1. PIN DESCRIPTION

Pin Name	Description
I	Input
Р	Power Supply, GND
NC	Not Connect
0	Output
В	Bidirection

• 2-wire serial interface

SCL I 2-wire serial interface clock pin SDA B 2-wire serial interface data pin

• Driver interface

OUT1 O Driver output (to Actuator)
OUT2 O Driver output (to Actuator)

• Power supply pin

VDD P Power Supply

VSS P GND

• Port pin

PORT B Convergence detection monitor output

VSYNC input

Test pin

• Test pin

TEST O Test pin

*Process when pins are not used

PIN TYPE "O" – Ensure that it is set to OPEN.

PIN TYPE "I" – OPEN is inhibited. Ensure that it is connected to the V_{DD} or V_{SS} even when it is unused.

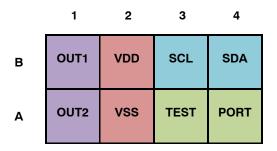
(Please contact **onsemi** for more information about selection of V_{DD} or V_{SS} .)

PIN TYPE "B" – If you are unsure about processing method on the pin description of pin layout table, please contact us.

Note that incorrect processing of unused pins may result in defects.

*In case of connecting PORT pin with HOST CPU When LC898219XI is power off and HOST CPU is power on, a HOST CPU pin connected with PORT pin have to be fixed "L" level.

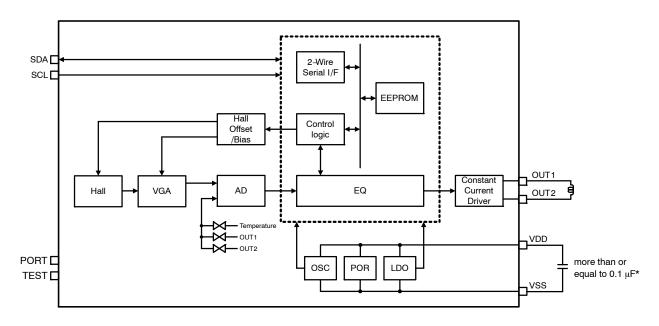
PIN LAYOUT



BOTTOM VIEW

Figure 1. Pin Layout

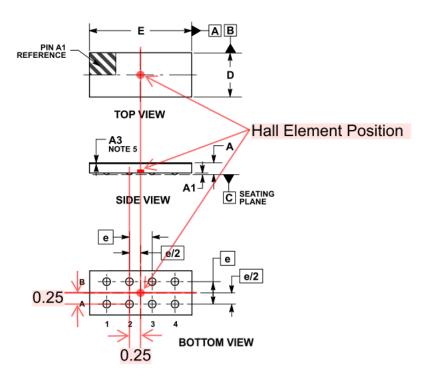
BLOCK DIAGRAM



^{*}Consider capacitance of capacitor between V_{DD} and V_{SS} . According to power source environment, attach an additional capacitor in camera module.

Figure 2. Block Diagram

HALL ELEMENT POSITION



unit: mm(typ)

Please refer to package diagram for each dimension.

Figure 3. Hall Element Position

ELECTRICAL CHARACTERISTICS

Table 2. ABSOLUTE MAXIMUM RATINGS ($V_{SS} = 0 \text{ V}$)

Symbol	Item	Condition	Rating	Unit
V _{DD} 33 max	Supply voltage	Ta ≤ 25°C	-0.3 to 4.6	V
V _I 33, V _O 33	Input/output voltage	Ta ≤ 25°C	-0.3 to V _{DD} 33 + 0.3	V
Tstg	Storage ambient temperature		-55 to 125	°C
Topr	Operating ambient temperature		-30 to 70	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. ACCEPTABLE OPERATING RANGES (Ta = -30 to 70°C, VSS = 0 V, 3 V power supply (V_{DD}))

Symbol	Item	Min	Тур	Max	Unit
V _{DD} 33	Supply voltage	2.6	2.8	3.3	V
V _{IN}	Input voltage range	0		V _{DD} 33	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. DC CHARACTERISTICS (Input / output level at V_{SS} = 0 V, V_{DD} = 2.6 to 3.3 V, Ta = -30 to 70°C)

Symbol	ltem	Condition	Min	Тур	Max	Unit	Applicable Pins
V _{IH}	High-level input voltage	CMOS compliant Schmitt	1.4			V	SCL, SDA,
V _{IL}	Low-level input voltage				0.4	V	PORT
V _{OH}	High-level output voltage	IOH = −2 mA	V _{DD} -0.4			V	PORT
V _{OL}	Low-level output voltage	IOL = 2 mA			0.2	V	SDA, PORT
Rdn	Pulldown resistor		50		220	kΩ	PORT

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 5. DRIVER OUTPUT (OUT1, OUT2) ($V_{SS} = 0 \text{ V}, V_{DD} = 2.8 \text{ V}, \text{ Ta} = 25^{\circ}\text{C}$)

Symbol	Item	Condition	Min	Тур	Max	Unit	Applicable Pins
Ifull	Maximum current		133	140	147	mA	OUT1, OUT2

Table 6. NON-VOLATILE MEMORY CHARACTERISTICS

Symbol	ltem	Condition	Min	Тур	Max	Unit	Applicable Circuit
EN	Endurance				1000	Cycles	EEPROM
RT	Data retention		10			Years	
tWT	Write time				20	ms	

AC CHARACTERISTICS

V_{DD} Supply Timing

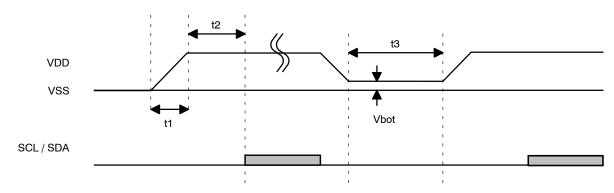


Figure 4. V_{DD} Supply Timing

It is available to use 2-wire serial interface 5 ms later for Power On Reset of V_{DD} .

Table 7. V_{DD} SUPPLY TIMING

Symbol	ltem	Min	Тур	Max	Unit
t1	V _{DD} turn on time			3	ms
t2	2-wire serial interface start time from V _{DD} on	5			ms
t3	V _{DD} off time	100			ms
Vbot	Bottom Voltage			0.1	V

AC Specification

Figure 5 shows interface timing definition and Table 8 shows electric characteristics.

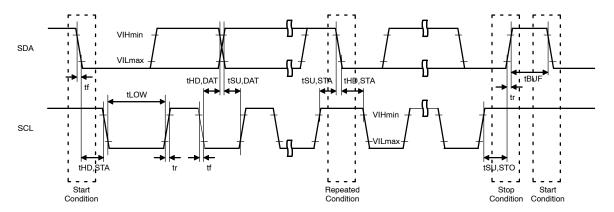


Figure 5. 2-wire Serial Interface Timing Definition

Table 8. ELECTRICAL CHARACTERISTICS FOR 2-WIRE SERIAL INTERFACE (AC CHARACTERISTICS)

		Pin	Fast-mode		Fas	st-mode F	lus		
Symbol	ltem	Name	Min	Тур	Max	Min	Тур	Max	Unit
FSCL	SCL clock frequency	SCL			400			1000	kHz
tHD,STA	START condition hold time	SCL SDA	0.6			0.26			μs
tLOW	SCL clock Low period	SCL	1.3			0.5			μs
tHIGH	SCL clock High period	SCL	0.6			0.26			μs
tSU,STA	Setup time for repetition START condition	SCL SDA	0.6			0.26			μs
tHD,DAT	Data hold time	SCL SDA	0 (Note 1)		0.9	0 (Note 1)			μs
tSU,DAT	Data setup time	SCL SDA	100			50			ns
tr	SDA, SCL rising time	SCL SDA			300			120	ns
tf	SDA, SCL falling time	SCL SDA			300			120	ns
tSU,STO	STOP condition setup time	SCL SDA	0.6			0.26			μs
tBUF	Bus free time between STOP and START	SCL SDA	1.3			0.5			μs

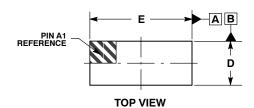
^{1.} LC898219XI is designed for a condition with typ. 20 ns of hold time. If SDA signal is unstable around falling point of SCL signal, please implement an appropriate treatment on board, such as inserting a resistor.

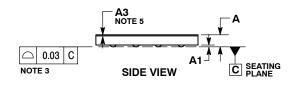


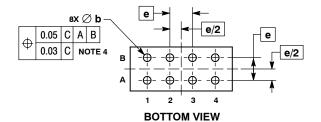
WLCSP8, 0.97x2.25X0.265

CASE 567TE **ISSUE A**

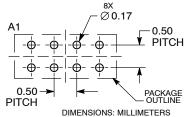
DATE 10 MAR 2017







RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DIMENSION 6 IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.
- DIMENSION A3 IS AN OPTIONAL BACKSIDE COATING LAYER.

	MILLIMETERS							
DIM	MIN	MIN NOM MAX						
Α	0.24	0.265	0.29					
A1		0.04 REF						
АЗ	(0.025 REI	=					
p	0.12	0.17	0.22					
D	0.92	0.97	1.02					
Е	2.20	2.20 2.25 2.30						
е	0.50 BSC							

GENERIC MARKING DIAGRAM*



= Assembly Location

WL = Wafer Lot

Υ = Year

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

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